

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2014 [Approved on 05 January 2026, 14:42 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.974%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.5%
			ALUMINUM, ELEMENTAL	7429-90-5	1%
			GOLD, ELEMENTAL	7440-57-5	1%
			Elemental silicon	7440-21-3	97.5%
Encapsulation	EP (Epoxy resin)	54.758%	Carbon black	1333-86-4	0.1%
			Phenol, polymer with formaldehyde	9003-35-4	5.8%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	9.1%
			Quartz sand	60676-86-0	85%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.258%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.573%	Tin	7440-31-5	100%
Leadframe	Highly alloyed cast iron	43.437%	Elemental zinc	7440-66-6	0.52%
			Nickel REACH Article 67 Exemption	7440-02-0	0.7%
			Tin elemental	7440-31-5	1%
			COPPER, ELEMENTAL	7440-50-8	97.78%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-363_Pb&H-free (AO)_01	Diode / Transistor	0.006978	g
